

Usage Policy

The edge bead removal process is equipment and substrate specific. Therefore, the following baseline process suggestions may be modified and optimized after considering the following:

- Wafer size
- Topside or backside EBR dispense
- Nozzle position and angle with respect to wafer edge
- Thickness of edge bead being removed
- Use Syringe for dispensing the resist

Process Guidelines

- a. After resist spin coat, reduce spin speed to 800rpm*.
- b. Dispense EBR PG, at ~3psi, for 3 seconds while maintaining 800rpm*.
- c. Ramp to 1000rpm** at 5000rpm/sec for 3-5 additional seconds of EBR dispense.
- d. Turn EBR dispense off.
- e. Accelerate to 2500rpm at 1000rpm/sec. Continue to spin for 10 seconds.
- g. Reduce spin speed to 0 at 1000rpm/sec.

*Increase spin speed for smaller wafers, e.g. 1000rpm for 4" wafers.

**1500rpm for 4" wafers.